

RESPONSE TO OFFICE ACTION
Serial No. 10/616,097
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Sun, et al.

ଶ୍ରୀମଦ୍ଭଗବତ

Case: AMAT/8241/CMP/ECP/RKK

Serial No.: 10/616,097

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Filed: July 8, 2003

Examiner: Edna Wong

கால்பந்து

Group Art Unit: 1753

Confirmation No.: 1645

ପ୍ରକାଶକ ମନ୍ତ୍ରୀ

**Title: MULTIPLE-STEP
ELECTRODEPOSITION PROCESS
FOR DIRECT COPPER PLATING ON
BARRIER MATERIALS**

**MAIL STOP Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450**

ପ୍ରକାଶକ ମାଲା

Dear Sir:

RESPONSE TO FINAL OFFICE ACTION DATED NOVEMBER 21, 2007

In response to the Final Office Action dated November 21, 2007 having a shortened statutory period for response set to expire on February 21, 2008, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Although the Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782 for any other fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

P.C.H.
22308
ATE, I
entered per
REC dated
2-21-08